

PCN Number:	20150729001	PCN Date:	07/30/2015
Title:	Datasheet update for TMP007		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification etc.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



TMP007

www.ti.com

SBOS685C – APRIL 2014 – REVISED JULY 2015

Changes from Revision B (May 2014) to Revision C

Page

• Changed <i>Features, Applications, and Description</i> sections	1
• Changed thermopile sensor portion of functional block diagram	1
• Changed Handling Ratings to ESD Ratings and moved storage temperature to Absolute Maximum Ratings	5
• Added "full angle" to clarify field of view parameter in Electrical Characteristics	6
• Changed Figure 2	7
• Changed thermopile sensor portion of functional block diagram	10
• Deleted last sentence from 2nd paragraph of <i>Field of View and Angular Response</i> section	12
• Added Figure 20	12
• Changed text in <i>Thermopile Principles and Operation</i> section to clarify temperature measurement	13
• Changed value in Stefan-Boltzman constant definition from 5.7 to 5.67 in Equation 5	14
• Changed C to C2 in Table 1	14
• Changed recalibration item 3 in <i>Calibration</i> section	15
• Changed recalibration item 8 in <i>Calibration</i> section	15
• Added <i>Sensor Voltage Format</i> section	16
• Added <i>Temperature Format</i> section	17
• Changed text in <i>Temperature Format</i> section to clarify temperature conversion to degrees Celsius	17
• Changed text in <i>Slave Receiver Mode</i> section	19
• Changed text in <i>Slave Transmitter Mode</i> section	19
• Changed Figure 24 to clarify timing	21
• Changed incorrect SDA timing in Figure 25	22
• Changed SDA timing in Figure 26	22
• Changed register names in Table 7 to match registers in the rest of document.	26
• Changed register 2 reset value	26
• Changed C coefficient to C2 coefficient in Table 7	26
• Added Manufacturer ID register	26

- Added missing numbers (3, 2, and 1) to bit descriptions for A1, A2, B0, B1, and B2 27
- Changed register names in Table 8 to match register names in rest of document 27
- Changed C coefficient to C2 coefficient in Table 8 27
- Changed Figure 31 bit register to show correct bit names 28
- Changed Figure 32 bit register reset values 28
- Added T_{OBJ} to all Object Temperature titles in data sheet 29
- Changed Figure 36 to Figure 39 bit register descriptions to show correct bit names 31
- Changed Figure 40 bit register reset values 32
- Deleted "Twos complement format" from S0 bit description 32
- Changed Figure 41 bit register reset values 32
- Changed Figure 42 bit register reset values 32
- Changed C to C2 in *C2 Coefficient Register* section 33
- Added Manufacturer ID register 34
- Changed Figure 50 bit register names and reset values 34
- Changed bit names in Figure 51 to match the text shown in Table 8 35
- Changed bit names in Figure 52 to match the text shown in Table 8 35
- Changed capacitor in Figure 53 from 0.01 μ F to 0.1 μ F 36
- Changed capacitor in Figure 56 from 0.01 μ F to 0.1 μ F 40
- Changed σ B to σ in Equation 20 to show correct Stefan-Boltzmann symbol 43
- Changed symbol for Stefan-Boltzmann constant from B to σ in Equation 20 43
- Changed decoupling capacitor in *Power-Supply Recommendations* section from 0.01 μ F to 0.1 μ F 44
- Changed title for Figure 61 46
- Deleted Figure 63, Bottom Layer 47

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP007	SBOS685B	SBOS685C

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TMP007>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP007AIYZFR	TMP007AIYZFT
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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